

## CLAIM AMENDMENTS

1-100 (cancelled)

1        101. (New) A method of making a semiconductor chip assembly, comprising:  
2        providing a metal base with first and second opposing surfaces; then  
3        forming an etch mask on the first surface of the metal base;  
4        forming a routing line on the second surface of the metal base; then  
5        etching the metal base, wherein an unetched portion of the metal base defined by the etch  
6        mask forms a pillar that includes first and second opposing surfaces, the first surface of the pillar  
7        faces away from the routing line and contacts the etch mask, and the second surface of the pillar  
8        contacts the routing line; then  
9        mechanically attaching a semiconductor chip to the routing line and the pillar, wherein  
10       the chip includes first and second opposing surfaces, the first surface of the chip includes a  
11       conductive pad, the first surface of the pillar faces in a first direction, the second surface of the  
12       pillar faces in a second direction opposite the first direction, the chip extends vertically beyond  
13       the routing line in the first direction, the pillar is disposed outside a periphery of the chip and  
14       extends vertically beyond the routing line in the first direction, and the routing line extends  
15       laterally from the pillar towards the chip;  
16       forming an encapsulant that covers the chip and extends vertically beyond the chip and  
17       the routing line in the first direction, wherein the encapsulant includes a first surface that faces in  
18       the first direction and a second surface that faces in the second direction, and the chip and the  
19       pillar are embedded in the encapsulant; and  
20       forming a connection joint that electrically connects the routing line and the pad, wherein  
21       a conductive trace that includes the routing line and the pillar is electrically connected to the pad  
22       and extends through the first surface of the encapsulant.

1        102. (New) The method of claim 101, wherein forming the routing line includes  
2        selectively depositing the routing line on the metal base.

1           103. (New) The method of claim 101, wherein forming the routing line includes:  
2           providing a plating mask on the metal base, wherein the plating mask includes an opening  
3 that exposes a portion of the metal base; and then  
4           electroplating the routing line on the exposed portion of the metal base through the  
5 opening in the plating mask.

1           104. (New) The method of claim 101, wherein forming the etch mask and the routing line  
2 includes simultaneously depositing the etch mask and the routing line on the metal base.

1           105. (New) The method of claim 101, wherein forming the etch mask and the routing line  
2 includes:  
3           providing a first plating mask on the metal base, wherein the first plating mask includes  
4 an opening that exposes a first portion of the metal base;  
5           providing a second plating mask on the metal base, wherein the second plating mask  
6 includes an opening that exposes a second portion of the metal base; and then  
7           simultaneously electroplating the etch mask on the first exposed portion of the metal base  
8 through the opening in the first plating mask and the routing line on the second exposed portion  
9 of the metal base through the opening in the second plating mask.

1           106. (New) The method of claim 101, wherein etching the metal base etches through the  
2 metal base.

1           107. (New) The method of claim 101, wherein etching the metal base exposes the routing  
2 line.

1           108. (New) The method of claim 101, wherein etching the metal base reduces contact  
2 area between the metal base and the routing line.

1           109. (New) The method of claim 101, wherein etching the metal base electrically isolates  
2 the routing line from other routing lines formed on the metal base.

1           110. (New) The method of claim 101, wherein forming the encapsulant includes  
2   depositing the encapsulant on the pillar such that the encapsulant covers the pillar.

1           111. (New) The method of claim 101, wherein forming the encapsulant includes  
2   depositing the encapsulant on the pillar such that the first surface of the pillar is exposed.

1           112. (New) The method of claim 101, including removing a portion of the encapsulant  
2   thereby exposing the pillar.

1           113. (New) The method of claim 112, wherein removing the portion of the encapsulant  
2   exposes the first surface of the pillar and laterally aligns the first surfaces of the encapsulant and  
3   the pillar with one another.

1           114. (New) The method of claim 101, including removing a portion of the encapsulant  
2   thereby exposing the chip.

1           115. (New) The method of claim 114, wherein removing the portion of the encapsulant  
2   exposes the second surface of the chip and laterally aligns the first surface of the encapsulant and  
3   the second surface of the chip with one another.

1           116. (New) The method of claim 101, wherein forming the connection joint includes  
2   electroplating the connection joint on the routing line and the pad.

1           117. (New) The method of claim 101, wherein forming the connection joint includes  
2   electrolessly plating the connection joint on the routing line and the pad.

1           118. (New) The method of claim 101, wherein forming the connection joint includes  
2   depositing a non-solidified material on the routing line and the pad and then hardening the non-  
3   solidified material.

1           119. (New) The method of claim 101, wherein forming the connection joint includes  
2 providing a wire bond that extends vertically beyond the chip and the routing line in the second  
3 direction.

1           120. (New) The method of claim 101, wherein forming the connection joint occurs before  
2 forming the encapsulant.

1           121. (New) The method of claim 101, wherein forming the connection joint occurs after  
2 forming the encapsulant.

1           122. (New) The method of claim 101, wherein the first surface of the chip faces in the  
2 first direction after mechanically attaching the chip to the routing line and the pillar.

1           123. (New) The method of claim 101, wherein the first surface of the chip faces in the  
2 second direction after mechanically attaching the chip to the routing line and the pillar.

1           124. (New) The method of claim 101, wherein the routing line extends vertically beyond  
2 the chip in the second direction after mechanically attaching the chip to the routing line and the  
3 pillar.

1           125. (New) The method of claim 101, wherein the routing line extends vertically beyond  
2 the pillar in the second direction after mechanically attaching the chip to the routing line and the  
3 pillar.

1           126. (New) The method of claim 101, wherein the routing line extends within and outside  
2 the periphery of the chip after mechanically attaching the chip to the routing line and the pillar.

1           127. (New) The method of claim 101, wherein the routing line is disposed outside the  
2 periphery of the chip after mechanically attaching the chip to the routing line and the pillar.

1           128. (New) The method of claim 101, wherein the first surface of the pillar extends  
2 vertically beyond the chip in the first direction after mechanically attaching the chip to the  
3 routing line and the pillar.

1           129. (New) The method of claim 101, wherein the second surface of the pillar extends  
2 vertically beyond the chip in the second direction after mechanically attaching the chip to the  
3 routing line and the pillar.

1           130. (New) The method of claim 101, wherein the metal base is a copper plate.

1           131. (New) The method of claim 101, wherein the routing line is an essentially planar  
2 metal lead.

1           132. (New) The method of claim 101, wherein the pillar has a conical shape.

1           133. (New) The method of claim 101, wherein the pillar is narrowest its first surface.

1           134. (New) The method of claim 101, wherein the pillar is widest at its second surface.

1           135. (New) The method of claim 101, wherein the pillar has tapered sidewalls that extend  
2 between its first and second surfaces and slant inwardly towards its first surface.

1           136. (New) The method of claim 101, wherein the pillar has a first surface area at its first  
2 surface and a second surface area at its second surface, and the first surface area is at least 20  
3 percent smaller than the second surface area.

1           137. (New) The method of claim 101, including forming an insulative base that contacts  
2 the metal base and the routing line before forming the pillar, wherein the insulative base extends

3 vertically beyond the chip, the routing line and the pillar in the second direction after  
4 mechanically attaching the chip to the routing line and the pillar.

1 138. (New) The method of claim 137, including forming a through-hole that extends  
2 through the insulative base and exposes the pad, and then forming the connection joint.

1 139. (New) The method of claim 101, including mechanically attaching the metal base  
2 and the routing line to a support before forming the pillar, and removing the support after  
3 forming the encapsulant.

1 140. (New) The method of claim 139, including removing the support before forming the  
2 connection joint.

1 141. (New) The method of claim 101, including mechanically attaching the chip to the  
2 routing line and the pillar using an insulative adhesive before forming the encapsulant.

1 142. (New) The method of claim 141, including forming a through-hole that extends  
2 through the adhesive and exposes the pad, and then forming the connection joint.

1 143. (New) The method of claim 142, wherein the adhesive contacts and is sandwiched  
2 between the routing line and the pad, and the routing line and the pad are electrically isolated  
3 from one another after forming the through-hole and before forming the connection joint.

1 144. (New) The method of claim 101, including simultaneously forming the connection  
2 joint and a first terminal that contacts the first surface of the pillar, extends vertically beyond the  
3 pillar in the first direction and is spaced from the connection joint during a plating operation.

1 145. (New) The method of claim 101, including simultaneously forming the connection  
2 joint and a second terminal that contacts the routing line, extends vertically beyond the routing  
3 line in the second direction and is spaced from the connection joint during a plating operation.

1           146. (New) The method of claim 101, including simultaneously forming the connection  
2 joint, a first terminal that contacts the first surface of the pillar, extends vertically beyond the  
3 pillar in the first direction and is spaced from the connection joint, and a second terminal that  
4 contacts the routing line, extends vertically beyond the routing line in the second direction and is  
5 spaced from the connection joint and the first terminal during a plating operation.

1           147. (New) The method of claim 146, including forming a first solder ball on the first  
2 terminal and a second solder ball on the second terminal.

1           148. (New) The method of claim 101, including mechanically attaching a heat sink to the  
2 chip, the routing line, the pillar, the encapsulant and the connection joint, wherein the heat sink is  
3 electrically isolated from the chip, overlapped by the chip and disposed vertically beyond the  
4 chip in the second direction.

1           149. (New) The method of claim 101, including mechanically attaching a ground plane to  
2 the chip, the routing line, the pillar, the encapsulant and the connection joint, and then electrically  
3 connecting the ground plane to the routing line, wherein the ground plane is overlapped by the  
4 routing line and disposed vertically beyond the routing line in the second direction.

1           150. (New) The method of claim 101, wherein the assembly is devoid of wire bonds and  
2 TAB leads.

1           151. (New) A method of making a semiconductor chip assembly, comprising:  
2 providing a metal base with first and second opposing surfaces; then  
3 forming an etch mask on the first surface of the metal base;  
4 forming a routing line on the second surface of the metal base; then  
5 etching the metal base, thereby etching through the metal base and reducing contact area  
6 between the metal base and the routing line, wherein an unetched portion of the metal base  
7 defined by the etch mask forms a pillar that includes first and second opposing surfaces, the first

8 surface of the pillar faces away from the routing line and contacts the etch mask, and the second  
9 surface of the pillar contacts the routing line; then

10 mechanically attaching a semiconductor chip to the routing line and the pillar, wherein  
11 the chip includes first and second opposing surfaces, the first surface of the chip includes a  
12 conductive pad, the first surface of the pillar faces in a first direction, the second surface of the  
13 pillar faces in a second direction opposite the first direction, the chip extends vertically beyond  
14 the routing line in the first direction, the pillar is disposed outside a periphery of the chip and  
15 extends vertically beyond the routing line in the first direction, and the routing line extends  
16 laterally from the pillar towards the chip;

17 forming an encapsulant that covers the chip and extends vertically beyond the chip and  
18 the routing line in the first direction, wherein the encapsulant includes a first surface that faces in  
19 the first direction and a second surface that faces in the second direction, and the chip and the  
20 pillar are embedded in the encapsulant; and

21 forming a connection joint that electrically connects the routing line and the pad, wherein  
22 a conductive trace that includes the routing line and the pillar is electrically connected to the pad  
23 and extends through the first surface of the encapsulant.

1 152. (New) The method of claim 151, wherein forming the etch mask and the routing line  
2 includes simultaneously electroplating the etch mask and the routing line on the metal base.

1 153. (New) The method of claim 151, wherein forming the etch mask and the routing line  
2 includes:

3 providing a first plating mask on the metal base, wherein the first plating mask includes  
4 an opening that exposes a first portion of the metal base;

5 providing a second plating mask on the metal base, wherein the second plating mask  
6 includes an opening that exposes a second portion of the metal base; and then

7 simultaneously electroplating the etch mask on the first exposed portion of the metal base  
8 through the opening in the first plating mask and the routing line on the second exposed portion  
9 of the metal base through the opening in the second plating mask.



1           154. (New) The method of claim 153, wherein the first and second plating masks are  
2 photoresist.

1           155. (New) The method of claim 151, wherein:  
2           the etch mask includes first and second metal layers, the first metal layer of the etch mask  
3 contacts the first surface of the metal base and has a different composition than the metal base,  
4 and the second metal layer of the etch mask contacts the first metal layer of the etch mask, has a  
5 different composition than the first metal layer of the etch mask and is spaced from the metal  
6 base; and  
7           the routing line includes first and second metal layers, the first metal layer of the routing  
8 line contacts the second surface of the metal base and has a different composition than the metal  
9 base, and the second metal layer of the routing line contacts the first metal layer of the routing  
10 line, has a different composition than the first metal layer of the routing line and is spaced from  
11 the metal base.

1           156. (New) The method of claim 155, wherein the metal base and the second metal layers  
2 have similar compositions.

1           157. (New) The method of claim 156, wherein the metal base and the second metal layers  
2 are copper, and the first metal layers are nickel.

1           158. (New) The method of claim 156, wherein etching the metal base includes applying a  
2 wet chemical etch that is highly selective of the metal base and the second metal layers with  
3 respect to the first metal layers, thereby forming the pillar, removing the second metal layer of  
4 the etch mask and exposing the first metal layer of the routing line without removing the second  
5 metal layer of the routing line.

1           159. (New) The method of claim 158, including applying a second wet chemical etch  
2 after forming the pillar that is selective of the first metal layers, thereby removing the etch mask,

3 removing an exposed portion of the first metal layer of the routing line and exposing the first  
4 surface of the pillar.

1 160. (New) The method of claim 159, wherein applying the second wet chemical etch  
2 occurs before mechanically attaching the chip to the routing line and the pillar.

1 161. (New) A method of making a semiconductor chip assembly, comprising:  
2 providing a metal base with first and second opposing surfaces; then  
3 forming an etch mask on the first surface of the metal base;  
4 forming a routing line on the second surface of the metal base; then  
5 etching the metal base, wherein an unetched portion of the metal base defined by the etch  
6 mask forms a pillar that includes first and second opposing surfaces, the first surface of the pillar  
7 faces away from the routing line and contacts the etch mask, and the second surface of the pillar  
8 contacts the routing line; then  
9 mechanically attaching a semiconductor chip to the routing line and the pillar, wherein  
10 the chip includes first and second opposing surfaces, the first surface of the chip includes a  
11 conductive pad, the first surface of the pillar faces in a first direction, the second surface of the  
12 pillar faces in a second direction opposite the first direction, the chip extends vertically beyond  
13 the routing line in the first direction, the pillar is disposed outside a periphery of the chip and  
14 extends vertically beyond the routing line in the first direction, and the routing line extends  
15 laterally from the pillar towards the chip;  
16 forming an encapsulant that covers the chip, the routing line and the pillar and extends  
17 vertically beyond the chip, the routing line and the pillar in the first direction, wherein the  
18 encapsulant includes a first surface that faces in the first direction and a second surface that faces  
19 in the second direction, and the chip and the pillar are embedded in the encapsulant;  
20 removing a portion of the encapsulant, thereby exposing the first surface of the pillar such  
21 that the chip and the pillar remain embedded in the encapsulant; and  
22 forming a connection joint that electrically connects the routing line and the pad, wherein  
23 a conductive trace that includes the routing line and the pillar is electrically connected to the pad  
24 and extends through the first surface of the encapsulant.

1           162. (New) The method of claim 161, wherein forming the encapsulant includes transfer  
2 molding the encapsulant.

1           163. (New) The method of claim 161, wherein forming the encapsulant includes curing  
2 the encapsulant.

1           164. (New) The method of claim 161, wherein removing the portion of the encapsulant  
2 includes applying a laser that ablates the encapsulant.

1           165. (New) The method of claim 161, wherein removing the portion of the encapsulant  
2 includes applying a plasma that etches the encapsulant.

1           166. (New) The method of claim 161, wherein removing the portion of the encapsulant  
2 includes grinding the encapsulant.

1           167. (New) The method of claim 166, wherein removing the portion of the encapsulant  
2 includes grinding the encapsulant without grinding the pillar, and then grinding the encapsulant  
3 and the pillar, and excludes grinding the chip.

1           168. (New) The method of claim 166, wherein removing the portion of the encapsulant  
2 includes grinding the encapsulant without grinding the pillar and without grinding the chip, and  
3 then grinding the encapsulant, the pillar and the chip.

1           169. (New) The method of claim 168, wherein removing the portion of the encapsulant  
2 includes grinding the encapsulant without grinding the pillar and without grinding the chip, then  
3 grinding the encapsulant and the pillar without grinding the chip, and then grinding the  
4 encapsulant, the pillar and the chip.

1           170. (New) The method of claim 168, wherein removing the portion of the encapsulant  
2 includes grinding the encapsulant without grinding the pillar and without grinding the chip, then  
3 grinding the encapsulant and the chip without grinding the pillar, and then grinding the  
4 encapsulant, the pillar and the chip.

1           171. (New) A method of making a semiconductor chip assembly, comprising:  
2 providing a metal base with first and second opposing surfaces; then  
3 forming an etch mask on the first surface of the metal base;  
4 forming a routing line on the second surface of the metal base;  
5 mechanically attaching the metal base, the etch mask and the routing line to a support  
6 using an insulative base, wherein the insulative base contacts and is sandwiched between the  
7 metal base and the support, and between the routing line and the support; then  
8 etching the metal base, wherein an unetched portion of the metal base defined by the etch  
9 mask forms a pillar that includes first and second opposing surfaces, the first surface of the pillar  
10 faces away from the routing line and contacts the etch mask, and the second surface of the pillar  
11 contacts the routing line; then  
12 mechanically attaching a semiconductor chip to the routing line and the pillar, wherein  
13 the chip includes first and second opposing surfaces, the first surface of the chip includes a  
14 conductive pad, the first surface of the pillar faces in a first direction, the second surface of the  
15 pillar faces in a second direction opposite the first direction, the chip overlaps the insulative base  
16 and the support and extends vertically beyond the routing line in the first direction, the pillar is  
17 disposed outside a periphery of the chip and extends vertically beyond the routing line in the first  
18 direction, the routing line extends laterally from the pillar towards the chip, the insulative base  
19 extends vertically beyond the chip, the routing line and the pillar in the second direction, and the  
20 support extends vertically beyond the insulative base in the second direction;  
21 forming an encapsulant that covers the chip and extends vertically beyond the chip and  
22 the routing line in the first direction, wherein the encapsulant includes a first surface that faces in  
23 the first direction and a second surface that faces in the second direction, and the chip and the  
24 pillar are embedded in the encapsulant;  
25 removing the support after forming the encapsulant; and

26           forming a connection joint that electrically connects the routing line and the pad, wherein  
27   a conductive trace that includes the routing line and the pillar is electrically connected to the pad  
28   and extends through the first surface of the encapsulant.

1           172. (New) The method of claim 171, wherein mechanically attaching the metal base, the  
2   etch mask and the routing line to the support includes contacting the insulative base to the metal  
3   base and the routing line, then contacting the insulative base to the support, and then curing the  
4   insulative base.

1           173. (New) The method of claim 171, wherein mechanically attaching the metal base, the  
2   etch mask and the routing line to the support includes contacting the insulative base to the  
3   support, then contacting the insulative base to the metal base and the routing line, and then curing  
4   the insulative base.

1           174. (New) The method of claim 171, wherein mechanically attaching the chip to the  
2   routing line and the pillar includes using an insulative adhesive that contacts and is sandwiched  
3   between the chip and the insulative base.

1           175. (New) The method of claim 171, wherein mechanically attaching the chip to the  
2   routing line and the pillar occurs after removing the etch mask.

1           176. (New) The method of claim 171, wherein mechanically attaching the chip to the  
2   routing line and the pillar occurs while forming the connection joint.

1           177. (New) The method of claim 171, wherein removing the support includes etching the  
2   support.

1           178. (New) The method of claim 171, wherein removing the support includes peeling-off  
2   the support.

1           179. (New) The method of claim 171, wherein removing the support occurs before  
2 forming the connection joint.

1           180. (New) The method of claim 171, wherein removing the support occurs after forming  
2 the connection joint.

1           181. (New) A method of making a semiconductor chip assembly, comprising:  
2 providing a metal base with first and second opposing surfaces; then  
3 forming an etch mask on the first surface of the metal base;  
4 forming a routing line on the second surface of the metal base;  
5 forming an insulative base that contacts the metal base and the routing line; then  
6 etching the metal base, wherein an unetched portion of the metal base defined by the etch  
7 mask forms a pillar that includes first and second opposing surfaces, the first surface of the pillar  
8 faces away from the routing line and contacts the etch mask, and the second surface of the pillar  
9 contacts the routing line; then

10           mechanically attaching a semiconductor chip to the routing line and the pillar using an  
11 insulative adhesive that contacts and is sandwiched between the chip and the insulative base,  
12 wherein the chip includes first and second opposing surfaces, the first surface of the chip  
13 includes a conductive pad, the first surface of the pillar and the second surface of the chip face in  
14 a first direction, the first surface of the chip and the second surface of the pillar face in a second  
15 direction opposite the first direction, the chip extends vertically beyond the routing line in the  
16 first direction, the pillar is disposed outside a periphery of the chip and extends vertically beyond  
17 the routing line in the first direction, the routing line extends laterally from the pillar towards the  
18 chip, the adhesive extends vertically beyond the chip in the second direction, and the insulative  
19 base extends vertically beyond the adhesive in the second direction; then

20           forming an encapsulant that covers the chip and extends vertically beyond the chip and  
21 the routing line in the first direction, wherein the encapsulant includes a first surface that faces in  
22 the first direction and a second surface that faces in the second direction, and the chip and the  
23 pillar are embedded in the encapsulant; then

24 forming a through-hole that extends through the insulative base and the adhesive and  
25 exposes the pad; and then  
26 forming a connection joint that electrically connects the routing line and the pad, wherein  
27 a conductive trace that includes the routing line and the pillar is electrically connected to the pad  
28 and extends through the first surface of the encapsulant.

1 182. (New) The method of claim 181, wherein forming the through-hole includes  
2 applying a laser that ablates the insulative base and the adhesive.

1 183. (New) The method of claim 181, wherein forming the through-hole includes  
2 applying a plasma that etches the insulative base and the adhesive.

1 184. (New) The method of claim 181, wherein forming the through-hole exposes the  
2 routing line, and the connection joint contacts the routing line in the through-hole.

1 185. (New) The method of claim 184, wherein forming the connection joint includes  
2 electroplating the connection joint on the routing line and the pad.

1 186. (New) The method of claim 184, wherein forming the connection joint includes  
2 electrolessly plating the connection joint on the routing line and the pad.

1 187. (New) The method of claim 184, wherein forming the connection joint includes  
2 depositing solder paste on the routing line and the pad and then reflowing the solder paste.

1 188. (New) The method of claim 184, wherein forming the connection joint includes  
2 depositing conductive adhesive on the routing line and the pad and then curing the conductive  
3 adhesive.

1 189. (New) The method of claim 181, wherein forming the through-hole does not expose  
2 the routing line, and the connection joint does not contact the routing line in the through-hole.

1           190. (New) The method of claim 189, wherein forming the connection joint includes  
2 providing a wire bond that extends into and is electrically connected to the pad in the through-  
3 hole, and extends out of and is electrically connected to the routing line outside the through-hole.

1           191. (New) A method of making a semiconductor chip assembly, comprising:  
2 providing a metal base with first and second opposing surfaces; then  
3 forming an etch mask on the first surface of the metal base;  
4 forming a routing line on the second surface of the metal base; then  
5 etching the metal base, wherein an unetched portion of the metal base defined by the etch  
6 mask forms a pillar that includes first and second opposing surfaces, the first surface of the pillar  
7 faces away from the routing line and contacts the etch mask, and the second surface of the pillar  
8 contacts the routing line; then

9           mechanically attaching a semiconductor chip to the routing line and the pillar, wherein  
10 the chip includes first and second opposing surfaces, the first surface of the chip includes a  
11 conductive pad, the first surface of the pillar faces in a first direction, the second surface of the  
12 pillar faces in a second direction opposite the first direction, the chip extends vertically beyond  
13 the routing line in the first direction, the pillar is disposed outside a periphery of the chip and  
14 extends vertically beyond the routing line in the first direction, and the routing line extends  
15 laterally from the pillar towards the chip; then

16           forming an encapsulant that covers the chip and extends vertically beyond the chip and  
17 the routing line in the first direction, wherein the encapsulant includes a first surface that faces in  
18 the first direction and a second surface that faces in the second direction, and the chip and the  
19 pillar are embedded in the encapsulant; and then

20           forming a connection joint that contacts and electrically connects the routing line and the  
21 pad and a first terminal that contacts the first surface of the pillar, extends vertically beyond the  
22 pillar in the first direction and is spaced from the connection joint during a plating operation,  
23 wherein a conductive trace that includes the routing line, the pillar and the first terminal is  
24 electrically connected to the pad and extends through the first surface of the encapsulant.



1           192. (New) The method of claim 191, wherein forming the connection joint and the first  
2 terminal includes simultaneously forming the connection joint and the first terminal during the  
3 plating operation.

1           193. (New) The method of claim 191, wherein forming the connection joint and the first  
2 terminal includes forming a second terminal that contacts the routing line, extends vertically  
3 beyond the routing line in the second direction and is spaced from the connection joint and the  
4 first terminal during the plating operation.

1           194. (New) The method of claim 193, wherein forming the connection joint and the first  
2 and second terminals includes simultaneously forming the connection joint and the first and  
3 second terminals during the plating operation.

1           195. (New) The method of claim 193, wherein the first and second terminals are  
2 vertically aligned with one another.

1           196. (New) The method of claim 193, wherein the first and second terminals are not  
2 vertically aligned with one another.

1           197. (New) The method of claim 191, wherein the first surfaces of the pillar and the  
2 encapsulant are laterally aligned with one another, and the first terminal extends vertically  
3 beyond the encapsulant in the first direction.

1           198. (New) The method of claim 193, wherein the second terminal extends vertically  
2 beyond the encapsulant in the second direction.

1           199. (New) The method of claim 191, including forming a first solder ball on the first  
2 terminal.

1           200. (New) The method of claim 193, including forming a first solder ball on the first  
2 terminal and a second solder ball on the second terminal.

1           201. (New) A method of making a semiconductor chip assembly, comprising:  
2           providing a metal base;  
3           forming a routing line on the metal base;  
4           etching the metal base, wherein an unetched portion of the metal base forms a pillar that  
5 includes first and second opposing surfaces, the first surface of the pillar faces away from the  
6 routing line and the second surface of the pillar contacts the routing line; then  
7           mechanically attaching a semiconductor chip to the routing line and the pillar, wherein  
8 the chip includes first and second opposing surfaces, the first surface of the chip includes a  
9 conductive pad, the first surface of the pillar faces in a first direction, the second surface of the  
10 pillar faces in a second direction opposite the first direction, the chip extends vertically beyond  
11 the routing line in the first direction, the pillar is disposed outside a periphery of the chip and  
12 extends vertically beyond the routing line in the first direction, and the routing line extends  
13 laterally from the pillar towards the chip;  
14           forming an encapsulant that covers the chip and extends vertically beyond the chip and  
15 the routing line in the first direction, wherein the encapsulant includes a first surface that faces in  
16 the first direction and a second surface that faces in the second direction, and the chip and the  
17 pillar are embedded in the encapsulant; and  
18           forming a connection joint that electrically connects the routing line and the pad, wherein  
19 a conductive trace that includes the routing line and the pillar is electrically connected to the pad  
20 and extends through the first surface of the encapsulant.

1           202. (New) The method of claim 201, wherein forming an etch mask and the routing line  
2 includes:  
3           providing a first plating mask on the metal base, wherein the first plating mask includes  
4 an opening that exposes a first portion of the metal base;  
5           providing a second plating mask on the metal base, wherein the second plating mask  
6 includes an opening that exposes a second portion of the metal base; and then

7 simultaneously electroplating the etch mask on the first exposed portion of the metal base  
8 through the opening in the first plating mask and the routing line on the second exposed portion  
9 of the metal base through the opening in the second plating mask.

1 203. (New) The method of claim 201, wherein etching the metal base etches through the  
2 metal base, reduces contact area between the metal base and the routing line, exposes the routing  
3 line and electrically isolates the routing line from other routing lines formed on the metal base.

1 204. (New) The method of claim 201, wherein mechanically attaching the chip to the  
2 routing line and the pillar provides that the routing line extends within and outside a periphery of  
3 the chip and is disposed vertically beyond the chip in the second direction.

1 205. (New) The method of claim 201, wherein mechanically attaching the chip to the  
2 routing line and the pillar provides that the routing line is disposed outside the periphery of the  
3 chip and vertically beyond the chip in the second direction.

1 206. (New) The method of claim 201, wherein mechanically attaching the chip to the  
2 routing line and the pillar provides that the first surface of the pillar extends vertically beyond the  
3 chip in the first direction.

1 207. (New) The method of claim 201, wherein mechanically attaching the chip to the  
2 routing line and the pillar provides that the second surface of the pillar extends vertically beyond  
3 the chip in the second direction.

1 208. (New) The method of claim 201, wherein forming the encapsulant includes  
2 depositing the encapsulant on and in contact with the chip and the pillar.

1 209. (New) The method of claim 201, wherein forming the encapsulant includes  
2 depositing the encapsulant such that the encapsulant covers the first surface of the pillar, and  
3 after depositing the encapsulant, the method includes grinding the first surface of the encapsulant

4 without grinding the pillar, and then grinding the first surfaces of the pillar and the encapsulant  
5 such that the first surfaces of the pillar and the encapsulant are laterally aligned with one another.

1 210. (New) The method of claim 201, wherein forming the encapsulant includes  
2 depositing the encapsulant such that the encapsulant does not cover the first surface of the pillar.

1 211. (New) The method of claim 201, wherein forming the connection joint occurs after  
2 forming the encapsulant.

1 212. (New) The method of claim 201, wherein forming the connection joint occurs after  
2 forming the encapsulant and removing a portion of the encapsulant to expose the first surface of  
3 the pillar.

1 213. (New) The method of claim 201, wherein forming the connection joint includes  
2 plating the connection joint on the routing line and the pad during a plating operation.

1 214. (New) The method of claim 213, including forming a first terminal that contacts the  
2 first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3 from the connection joint during the plating operation.

1 215. (New) The method of claim 214, including forming a second terminal that contacts  
2 the routing line, extends vertically beyond the routing line in the second direction and is spaced  
3 from the connection joint and the first terminal during the plating operation.

1 216. (New) The method of claim 201, wherein the routing line is an essentially flat planar  
2 lead, and the pillar has tapered sidewalls that extend between its first and second surfaces and  
3 extend inwardly towards its first surface.

1 217. (New) The method of claim 201, including mechanically attaching a heat sink to the  
2 chip, the routing line, the pillar, the encapsulant and the connection joint, wherein the heat sink is

3 electrically isolated from the chip, overlapped by the chip and disposed vertically beyond the  
4 chip in the second direction.

1 218. (New) The method of claim 217, including forming a first terminal that contacts the  
2 first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3 from the connection joint and a metallic coating that contacts the heat sink, extends vertically  
4 beyond the heat sink in the second direction and is spaced from the first terminal and the  
5 connection joint during a plating operation.

1 219. (New) The method of claim 201, including mechanically attaching a ground plane to  
2 the chip, the routing line, the pillar, the encapsulant and the connection joint, and then electrically  
3 connecting the ground plane to the routing line, wherein the ground plane is overlapped by the  
4 routing line and disposed vertically beyond the routing line in the second direction.

1 220. (New) The method of claim 219, including forming a first terminal that contacts the  
2 first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3 from the connection joint and a metallic coating that contacts and electrically connects the  
4 routing line and the ground plane, extends vertically beyond the ground plane in the second  
5 direction and is spaced from the first terminal and the connection joint during a plating operation.

1 221. (New) A method of making a semiconductor chip assembly, comprising the  
2 following steps in the sequence set forth:  
3 providing a metal base with first and second opposing surfaces;  
4 forming an etch mask on the first surface of the metal base and a routing line on the  
5 second surface of the metal base;  
6 mechanically attaching the metal base, the etch mask and the routing line to a support  
7 using an insulative base that extends between the metal base and the support, and between the  
8 routing line and the support;  
9 etching the metal base, wherein an unetched portion of the metal base defined by the etch  
10 mask forms a pillar that includes first and second opposing surfaces, the first surface of the pillar

11 faces away from the routing line and contacts the etch mask, and the second surface of the pillar  
12 contacts the routing line;

13 mechanically attaching a semiconductor chip to the routing line and the pillar using an  
14 adhesive that extends between the chip and the insulative base, wherein the chip includes first  
15 and second opposing surfaces, the first surface of the chip includes a conductive pad, the first  
16 surface of the pillar and the second surface of the chip face in a first direction, the first surface of  
17 the chip and the second surface of the pillar face in a second direction opposite the first direction,  
18 the chip, the routing line and the pillar overlap the insulative base and the support, the chip  
19 extends vertically beyond the routing line in the first direction, the pillar is disposed outside a  
20 periphery of the chip and extends vertically beyond the routing line and the first surface of the  
21 chip in the first direction, the routing line extends laterally from the pillar towards the chip and  
22 extends within and outside the periphery of the chip, the insulative base extends vertically  
23 beyond the chip, the routing line and the pillar in the second direction, and the support extends  
24 vertically beyond the insulative base in the second direction;

25 forming an encapsulant that covers the chip and extends vertically beyond the chip and  
26 the routing line in the first direction, wherein the encapsulant includes a first surface that faces in  
27 the first direction and a second surface that faces in the second direction, and the chip and the  
28 pillar are embedded in the encapsulant;

29 removing the support;

30 forming a through-hole that extends through the insulative base and the adhesive and  
31 exposes the routing line and the pad; and

32 forming a connection joint that electrically connects the routing line and the pad in the  
33 through-hole, wherein a conductive trace that includes the routing line and the pillar is  
34 electrically connected to the pad and extends through the first surface of the encapsulant.

1 222. (New) The method of claim 221, wherein forming the etch mask and the routing line  
2 includes:

3 providing a first plating mask on the metal base, wherein the first plating mask includes  
4 an opening that exposes a first portion of the metal base;

5 providing a second plating mask on the metal base, wherein the second plating mask  
6 includes an opening that exposes a second portion of the metal base; and then  
7 simultaneously electroplating the etch mask on the first exposed portion of the metal base  
8 through the opening in the first plating mask and the routing line on the second exposed portion  
9 of the metal base through the opening in the second plating mask.

1 223. (New) The method of claim 221, wherein etching the metal base etches through the  
2 metal base, reduces contact area between the metal base and the routing line, exposes the routing  
3 line and electrically isolates the routing line from other routing lines formed on the metal base.

1 224. (New) The method of claim 221, wherein mechanically attaching the chip to the  
2 routing line and the pillar provides that the first surface of the pillar extends vertically beyond the  
3 chip in the first direction.

1 225. (New) The method of claim 221, wherein mechanically attaching the chip to the  
2 routing line and the pillar provides that the second surface of the pillar extends vertically beyond  
3 the chip in the second direction.

1 226. (New) The method of claim 221, wherein removing the support includes etching the  
2 support.

1 227. (New) The method of claim 221, wherein removing the support includes peeling-off  
2 the support.

1 228. (New) The method of claim 221, wherein forming the encapsulant includes  
2 depositing the encapsulant on and in contact with the chip, the pillar and the insulative base.

1 229. (New) The method of claim 221, wherein forming the encapsulant includes  
2 depositing the encapsulant such that the encapsulant covers the first surface of the pillar, and  
3 after depositing the encapsulant, the method includes grinding the first surface of the encapsulant

4 without grinding the pillar, and then grinding the first surfaces of the pillar and the encapsulant  
5 such that the first surfaces of the pillar and the encapsulant are laterally aligned with one another.

1 230. (New) The method of claim 221, wherein forming the encapsulant includes  
2 depositing the encapsulant such that the encapsulant does not cover the first surface of the pillar.

1 231. (New) The method of claim 221, wherein forming the through-hole includes  
2 applying a laser that ablates the insulative base and the adhesive.

1 232. (New) The method of claim 221, wherein forming the through-hole includes  
2 applying a plasma that etches the insulative base and the adhesive.

1 233. (New) The method of claim 221, wherein forming the connection joint includes  
2 plating the connection joint on the routing line and the pad during a plating operation.

1 234. (New) The method of claim 233, including forming a first terminal that contacts the  
2 first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3 from the connection joint during the plating operation.

1 235. (New) The method of claim 234, including forming a second terminal that contacts  
2 the routing line, extends vertically beyond the routing line in the second direction and is spaced  
3 from the connection joint and the first terminal during the plating operation.

1 236. (New) The method of claim 221, wherein the routing line is an essentially flat planar  
2 lead, and the pillar has tapered sidewalls that extend between its first and second surfaces and  
3 extend inwardly towards its first surface.

1 237. (New) The method of claim 221, including mechanically attaching a heat sink to the  
2 insulative base after removing the support, wherein the heat sink is electrically isolated from the



3 chip, overlapped by the chip and disposed vertically beyond the insulative base the second  
4 direction.

1 238. (New) The method of claim 237, including forming a first terminal that contacts the  
2 first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3 from the connection joint and a metallic coating that contacts the heat sink, extends vertically  
4 beyond the heat sink in the second direction and is spaced from the first terminal and the  
5 connection joint during a plating operation.

1 239. (New) The method of claim 221, including mechanically attaching a ground plane to  
2 the insulative base after removing the support, and then electrically connecting the ground plane  
3 to the routing line, wherein the ground plane is overlapped by the routing line and disposed  
4 vertically beyond the insulative base in the second direction.

1 240. (New) The method of claim 239, including forming a first terminal that contacts the  
2 first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3 from the connection joint and a metallic coating that contacts and electrically connects the  
4 routing line and the ground plane, extends through the insulative base, extends vertically beyond  
5 the ground plane in the second direction and is spaced from the first terminal and the connection  
6 joint during a plating operation.

1 241. (New) A method of making a semiconductor chip assembly, comprising the  
2 following steps in the sequence set forth:  
3 providing a metal base with first and second opposing surfaces;  
4 forming an etch mask on the first surface of the metal base and a routing line on the  
5 second surface of the metal base;  
6 mechanically attaching the metal base, the etch mask and the routing line to a support  
7 using an insulative base that extends between the metal base and the support, and between the  
8 routing line and the support;

9 etching the metal base, wherein an unetched portion of the metal base defined by the etch  
10 mask forms a pillar that includes first and second opposing surfaces, the first surface of the pillar  
11 faces away from the routing line and contacts the etch mask, and the second surface of the pillar  
12 contacts the routing line;

13 mechanically attaching a semiconductor chip to the routing line and the pillar, wherein  
14 the chip includes first and second opposing surfaces, the first surface of the chip includes a  
15 conductive pad, the first surface of the pillar and the second surface of the chip face in a first  
16 direction, the first surface of the chip and the second surface of the pillar face in a second  
17 direction opposite the first direction, the chip, the routing line and the pillar overlap the insulative  
18 base and the support, the chip extends vertically beyond the routing line in the first direction, the  
19 pillar is disposed outside a periphery of the chip and extends vertically beyond the routing line  
20 and the first surface of the chip in the first direction, the routing line extends laterally from the  
21 pillar towards the chip and extends within and outside a periphery of the chip, the insulative base  
22 extends vertically beyond the chip, the routing line and the pillar in the second direction, the  
23 support extends vertically beyond the insulative base in the second direction, and a connection  
24 joint electrically connects the routing line and the pad;

25 forming an encapsulant that covers the chip and extends vertically beyond the chip and  
26 the routing line in the first direction, wherein the encapsulant includes a first surface that faces in  
27 the first direction and a second surface that faces in the second direction, and the chip and the  
28 pillar are embedded in the encapsulant; and

29 removing the support, wherein a conductive trace that includes the routing line and the  
30 pillar is electrically connected to the pad and extends through the first surface of the encapsulant.

1 242. (New) The method of claim 241, wherein forming the etch mask and the routing line  
2 includes:

3 providing a first plating mask on the metal base, wherein the first plating mask includes  
4 an opening that exposes a first portion of the metal base;

5 providing a second plating mask on the metal base, wherein the second plating mask  
6 includes an opening that exposes a second portion of the metal base; and then

7 simultaneously electroplating the etch mask on the first exposed portion of the metal base  
8 through the opening in the first plating mask and the routing line on the second exposed portion  
9 of the metal base through the opening in the second plating mask.

1 243. (New) The method of claim 241, wherein etching the metal base etches through the  
2 metal base, reduces contact area between the metal base and the routing line, exposes the routing  
3 line and electrically isolates the routing line from other routing lines formed on the metal base.

1 244. (New) The method of claim 241, wherein mechanically attaching the chip to the  
2 routing line and the pillar provides that the first surface of the pillar extends vertically beyond the  
3 chip in the first direction.

1 245. (New) The method of claim 241, wherein mechanically attaching the chip to the  
2 routing line and the pillar provides that the second surface of the pillar extends vertically beyond  
3 the chip in the second direction.

1 246. (New) The method of claim 241, wherein removing the support includes etching the  
2 support.

1 247. (New) The method of claim 241, wherein removing the support includes peeling-off  
2 the support.

1 248. (New) The method of claim 241, wherein forming the encapsulant includes  
2 depositing the encapsulant on and in contact with the chip, the pillar and the insulative base.

1 249. (New) The method of claim 241, wherein forming the encapsulant includes  
2 depositing the encapsulant such that the encapsulant covers the first surface of the pillar, and  
3 after depositing the encapsulant, the method includes grinding the first surface of the encapsulant  
4 without grinding the pillar, and then grinding the first surfaces of the pillar and the encapsulant  
5 such that the first surfaces of the pillar and the encapsulant are laterally aligned with one another.

1           250. (New) The method of claim 241, wherein forming the encapsulant includes  
2   depositing the encapsulant such that the encapsulant does not cover the first surface of the pillar.

1           251. (New) The method of claim 241, including forming a through-hole that extends  
2   through the insulative base and exposes the routing line after removing the support.

1           252. (New) The method of claim 251, wherein forming the through-hole includes  
2   applying a laser that ablates the insulative base.

1           253. (New) The method of claim 251, wherein forming the through-hole includes  
2   applying a plasma that etches the insulative base.

1           254. (New) The method of claim 251, including forming a second terminal that contacts  
2   the routing line in the through-hole, extends vertically beyond the routing line in the second  
3   direction and is spaced from the connection joint during a plating operation.

1           255. (New) The method of claim 254, including forming a first terminal that contacts the  
2   first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3   from the connection joint and the second terminal during the plating operation.

1           256. (New) The method of claim 241, wherein the routing line is an essentially flat planar  
2   lead, and the pillar has tapered sidewalls that extend between its first and second surfaces and  
3   extend inwardly towards its first surface.

1           257. (New) The method of claim 241, including mechanically attaching a heat sink to the  
2   insulative base after removing the support, wherein the heat sink is electrically isolated from the  
3   chip, overlapped by the chip and disposed vertically beyond the insulative base the second  
4   direction.

1           258. (New) The method of claim 257, including forming a first terminal that contacts the  
2 first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3 from the connection joint and a metallic coating that contacts the heat sink, extends vertically  
4 beyond the heat sink in the second direction and is spaced from the first terminal and the  
5 connection joint during a plating operation.

1           259. (New) The method of claim 241, including mechanically attaching a ground plane to  
2 the insulative base after removing the support, and then electrically connecting the ground plane  
3 to the routing line, wherein the ground plane is overlapped by the routing line and disposed  
4 vertically beyond the insulative base in the second direction.

1           260. (New) The method of claim 259, including forming a first terminal that contacts the  
2 first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3 from the connection joint and a metallic coating that contacts and electrically connects the  
4 routing line and the ground plane, extends through the insulative base, extends vertically beyond  
5 the ground plane in the second direction and is spaced from the first terminal and the connection  
6 joint during a plating operation.

1           261. (New) A method of making a semiconductor chip assembly, comprising the  
2 following steps in the sequence set forth:

3           providing a metal base with first and second opposing surfaces;

4           forming an etch mask on the first surface of the metal base and a routing line on the  
5 second surface of the metal base;

6           mechanically attaching the metal base, the etch mask and the routing line to a support  
7 using an insulative base that extends between the metal base and the support, and between the  
8 routing line and the support;

9           etching the metal base, wherein an unetched portion of the metal base defined by the etch  
10 mask forms a pillar that includes first and second opposing surfaces, the first surface of the pillar  
11 faces away from the routing line and contacts the etch mask, and the second surface of the pillar  
12 contacts the routing line;

13 mechanically attaching a semiconductor chip to the routing line and the pillar using an  
14 adhesive that extends between the chip and the insulative base, wherein the chip includes first  
15 and second opposing surfaces, the first surface of the chip includes a conductive pad, the first  
16 surface of the pillar and the second surface of the chip face in a first direction, the first surface of  
17 the chip and the second surface of the pillar face in a second direction opposite the first direction,  
18 the chip, the routing line and the pillar overlap the insulative base and the support, the chip  
19 extends vertically beyond the routing line in the first direction, the pillar is disposed outside a  
20 periphery of the chip and extends vertically beyond the routing line and the first surface of the  
21 chip in the first direction, the routing line extends laterally from the pillar towards the chip, the  
22 insulative base extends vertically beyond the chip, the routing line and the pillar in the second  
23 direction, and the support extends vertically beyond the insulative base in the second direction;  
24 forming an encapsulant that covers the chip and extends vertically beyond the chip and  
25 the routing line in the first direction, wherein the encapsulant includes a first surface that faces in  
26 the first direction and a second surface that faces in the second direction, and the chip and the  
27 pillar are embedded in the encapsulant;  
28 removing the support;  
29 forming a first through-hole that extends through the insulative base and exposes the  
30 routing line without exposing the pad and a second through-hole that extends through the  
31 insulative base and the adhesive and exposes the pad without exposing the routing line; and  
32 forming a wire bond connection joint that electrically connects the routing line and the  
33 pad, wherein the connection joint is electrically connected to the routing line in the first through-  
34 hole and the pad in the second through-hole, the connection joint extends vertically beyond the  
35 insulative base in the second direction, and a conductive trace that includes the routing line and  
36 the pillar is electrically connected to the pad and extends through the first surface of the  
37 encapsulant.

1 262. (New) The method of claim 261, wherein forming the etch mask and the routing line  
2 includes:  
3 providing a first plating mask on the metal base, wherein the first plating mask includes  
4 an opening that exposes a first portion of the metal base;

5 providing a second plating mask on the metal base, wherein the second plating mask  
6 includes an opening that exposes a second portion of the metal base; and then  
7 simultaneously electroplating the etch mask on the first exposed portion of the metal base  
8 through the opening in the first plating mask and the routing line on the second exposed portion  
9 of the metal base through the opening in the second plating mask.

1 263. (New) The method of claim 261, wherein etching the metal base etches through the  
2 metal base, reduces contact area between the metal base and the routing line, exposes the routing  
3 line and electrically isolates the routing line from other routing lines formed on the metal base.

1 264. (New) The method of claim 261, wherein mechanically attaching the chip to the  
2 routing line and the pillar provides that the first surface of the pillar extends vertically beyond the  
3 chip in the first direction.

1 265. (New) The method of claim 261, wherein mechanically attaching the chip to the  
2 routing line and the pillar provides that the second surface of the pillar extends vertically beyond  
3 the chip in the second direction.

1 266. (New) The method of claim 261, wherein removing the support includes etching the  
2 support.

1 267. (New) The method of claim 261, wherein removing the support includes peeling-off  
2 the support.

1 268. (New) The method of claim 261, wherein forming the encapsulant includes  
2 depositing the encapsulant on and in contact with the chip, the pillar and the insulative base.

1 269. (New) The method of claim 261, wherein forming the encapsulant includes  
2 depositing the encapsulant such that the encapsulant covers the first surface of the pillar, and  
3 after depositing the encapsulant, the method includes grinding the first surface of the encapsulant

4 without grinding the pillar, and then grinding the first surfaces of the pillar and the encapsulant  
5 such that the first surfaces of the pillar and the encapsulant are laterally aligned with one another.

1 270. (New) The method of claim 261, wherein forming the encapsulant includes  
2 depositing the encapsulant such that the encapsulant does not cover the first surface of the pillar.

1 271. (New) The method of claim 261, wherein forming the first through-hole includes  
2 applying a laser that ablates the insulative base, and forming the second through-hole includes  
3 applying a laser that ablates the insulative base and the adhesive.

1 272. (New) The method of claim 261, wherein forming the first through-hole includes  
2 applying a plasma that etches the insulative base, and forming the second through-hole includes  
3 applying a plasma that etches the insulative base and the adhesive.

1 273. (New) The method of claim 261, wherein forming the first and second through-holes  
2 includes forming the first and second through-holes in sequence.

1 274. (New) The method of claim 261, including forming a second terminal that contacts  
2 the routing line in the first through-hole and extends vertically beyond the routing line in the  
3 second direction during a plating operation, and then forming the connection joint on the second  
4 terminal.

1 275. (New) The method of claim 274, including forming a first terminal that contacts the  
2 first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3 from the second terminal during the plating operation.

1 276. (New) The method of claim 261, wherein the routing line is an essentially flat planar  
2 lead, and the pillar has tapered sidewalls that extend between its first and second surfaces and  
3 extend inwardly towards its first surface.



1           277. (New) The method of claim 261, including mechanically attaching a heat sink to the  
2 insulative base after removing the support, wherein the heat sink is electrically isolated from the  
3 chip, overlapped by the chip and disposed vertically beyond the insulative base the second  
4 direction.

1           278. (New) The method of claim 277, including forming a first terminal that contacts the  
2 first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3 from the connection joint and a metallic coating that contacts the heat sink, extends vertically  
4 beyond the heat sink in the second direction and is spaced from the first terminal and the  
5 connection joint during a plating operation.

1           279. (New) The method of claim 261, including mechanically attaching a ground plane to  
2 the insulative base after removing the support, and then electrically connecting the ground plane  
3 to the routing line, wherein the ground plane is overlapped by the routing line and disposed  
4 vertically beyond the insulative base in the second direction.

1           280. (New) The method of claim 279, including forming a first terminal that contacts the  
2 first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3 from the connection joint and a metallic coating that contacts and electrically connects the  
4 routing line and the ground plane, extends through the insulative base, extends vertically beyond  
5 the ground plane in the second direction and is spaced from the first terminal and the connection  
6 joint during a plating operation.

1           281. (New) A method of making a semiconductor chip assembly, comprising the  
2 following steps in the sequence set forth:  
3           providing a metal base with first and second opposing surfaces;  
4           forming an etch mask on the first surface of the metal base and a routing line on the  
5 second surface of the metal base;

6 mechanically attaching the metal base, the etch mask and the routing line to a support  
7 using an insulative base that extends between the metal base and the support, and between the  
8 routing line and the support;

9 etching the metal base, wherein an unetched portion of the metal base defined by the etch  
10 mask forms a pillar that includes first and second opposing surfaces, the first surface of the pillar  
11 faces away from the routing line and contacts the etch mask, and the second surface of the pillar  
12 contacts the routing line;

13 mechanically attaching a semiconductor chip to the routing line and the pillar using an  
14 adhesive that extends between the chip and the insulative base, wherein the chip includes first  
15 and second opposing surfaces, the first surface of the chip includes a conductive pad, the first  
16 surfaces of the chip and the pillar face in a first direction, the second surfaces of the chip and the  
17 pillar face in a second direction opposite the first direction, the chip, the routing line and the  
18 pillar overlap the insulative base and the support, the chip extends vertically beyond the routing  
19 line in the first direction, the pillar is disposed outside a periphery of the chip and extends  
20 vertically beyond the routing line and the second surface of the chip in the first direction, the  
21 routing line extends laterally from the pillar towards the chip, the insulative base extends  
22 vertically beyond the chip, the routing line and the pillar in the second direction, and the support  
23 extends vertically beyond the insulative base in the second direction;

24 forming a wire bond connection joint that electrically connects the routing line and the  
25 pad;

26 forming an encapsulant that covers the chip and the connection joint and extends  
27 vertically beyond the chip, the routing line and the connection joint in the first direction, wherein  
28 the encapsulant includes a first surface that faces in the first direction and a second surface that  
29 faces in the second direction, and the chip and the pillar are embedded in the encapsulant; and

30 removing the support, wherein a conductive trace that includes the routing line and the  
31 pillar is electrically connected to the pad and extends through the first surface of the encapsulant.

1 282. (New) The method of claim 281, wherein forming the etch mask and the routing line  
2 includes:

3 providing a first plating mask on the metal base, wherein the first plating mask includes  
4 an opening that exposes a first portion of the metal base;  
5 providing a second plating mask on the metal base, wherein the second plating mask  
6 includes an opening that exposes a second portion of the metal base; and then  
7 simultaneously electroplating the etch mask on the first exposed portion of the metal base  
8 through the opening in the first plating mask and the routing line on the second exposed portion  
9 of the metal base through the opening in the second plating mask.

1 283. (New) The method of claim 281, wherein etching the metal base etches through the  
2 metal base, reduces contact area between the metal base and the routing line, exposes the routing  
3 line and electrically isolates the routing line from other routing lines formed on the metal base.

1 284. (New) The method of claim 281, wherein mechanically attaching the chip to the  
2 routing line and the pillar provides that the first surface of the pillar extends vertically beyond the  
3 chip in the first direction.

1 285. (New) The method of claim 281, wherein mechanically attaching the chip to the  
2 routing line and the pillar provides that the second surface of the pillar extends vertically beyond  
3 the chip in the second direction.

1 286. (New) The method of claim 281, wherein removing the support includes etching the  
2 support.

1 287. (New) The method of claim 281, wherein removing the support includes peeling-off  
2 the support.

1 288. (New) The method of claim 281, wherein forming the encapsulant includes  
2 depositing the encapsulant on and in contact with the chip, the insulative base and the connection  
3 joint.

1           289. (New) The method of claim 281, wherein forming the encapsulant includes  
2   depositing the encapsulant such that the encapsulant covers the first surface of the pillar, and  
3   after depositing the encapsulant, the method includes grinding the first surface of the encapsulant  
4   without grinding the pillar, and then grinding the first surfaces of the pillar and the encapsulant  
5   such that the first surfaces of the pillar and the encapsulant are laterally aligned with one another.

1           290. (New) The method of claim 281, wherein forming the encapsulant includes  
2   depositing the encapsulant such that the encapsulant does not cover the first surface of the pillar.

1           291. (New) The method of claim 281, including forming a through-hole that extends  
2   through the insulative base and exposes the routing line after removing the support.

1           292. (New) The method of claim 291, wherein forming the through-hole includes  
2   applying a laser that ablates the insulative base.

1           293. (New) The method of claim 291, wherein forming the through-hole includes  
2   applying a plasma that etches the insulative base.

1           294. (New) The method of claim 291, including forming a second terminal that contacts  
2   the routing line in the through-hole, extends vertically beyond the routing line in the second  
3   direction and is spaced from the connection joint during a plating operation.

1           295. (New) The method of claim 294, including forming a first terminal that contacts the  
2   first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3   from the connection joint and the second terminal during the plating operation.

1           296. (New) The method of claim 281, wherein the routing line is an essentially flat planar  
2   lead, and the pillar has tapered sidewalls that extend between its first and second surfaces and  
3   extend inwardly towards its first surface.

1           297. (New) The method of claim 281, including mechanically attaching a heat sink to the  
2 insulative base after removing the support, wherein the heat sink is electrically isolated from the  
3 chip, overlapped by the chip and disposed vertically beyond the insulative base the second  
4 direction.

1           298. (New) The method of claim 297, including forming a first terminal that contacts the  
2 first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3 from the connection joint and a metallic coating that contacts the heat sink, extends vertically  
4 beyond the heat sink in the second direction and is spaced from the first terminal and the  
5 connection joint during a plating operation.

1           299. (New) The method of claim 281, including mechanically attaching a ground plane to  
2 the insulative base after removing the support, and then electrically connecting the ground plane  
3 to the routing line, wherein the ground plane is overlapped by the routing line and disposed  
4 vertically beyond the insulative base in the second direction.

1           300. (New) The method of claim 299, including forming a first terminal that contacts the  
2 first surface of the pillar, extends vertically beyond the pillar in the first direction and is spaced  
3 from the connection joint and a metallic coating that contacts and electrically connects the  
4 routing line and the ground plane, extends through the insulative base, extends vertically beyond  
5 the ground plane in the second direction and is spaced from the first terminal and the connection  
6 joint during a plating operation.